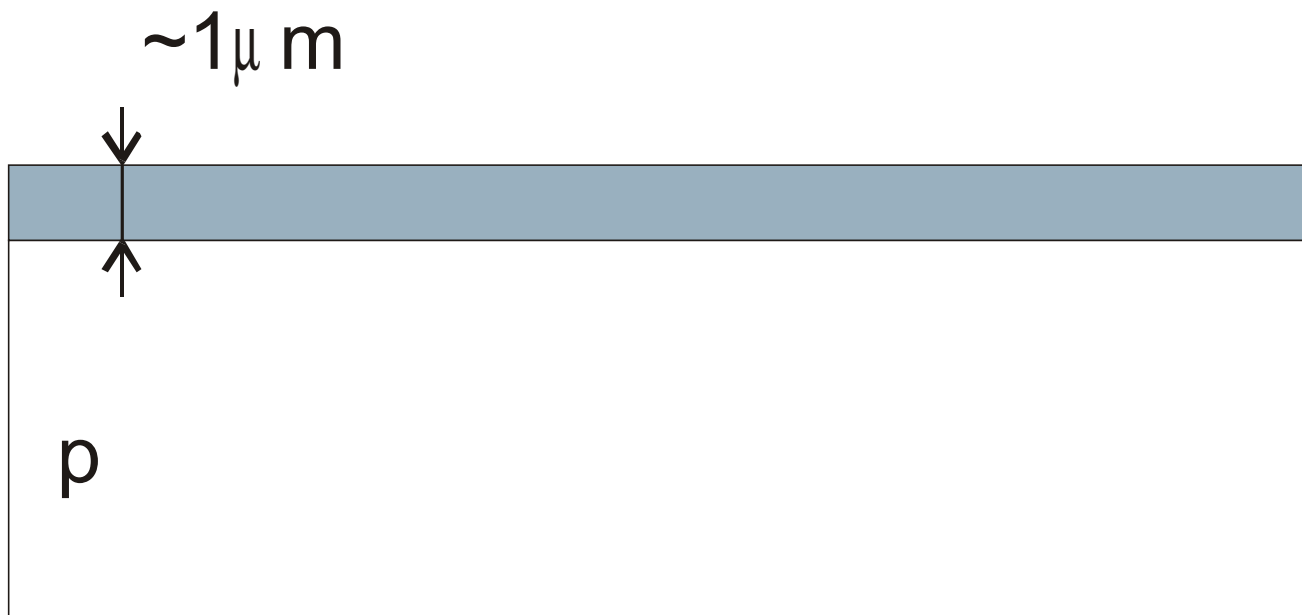
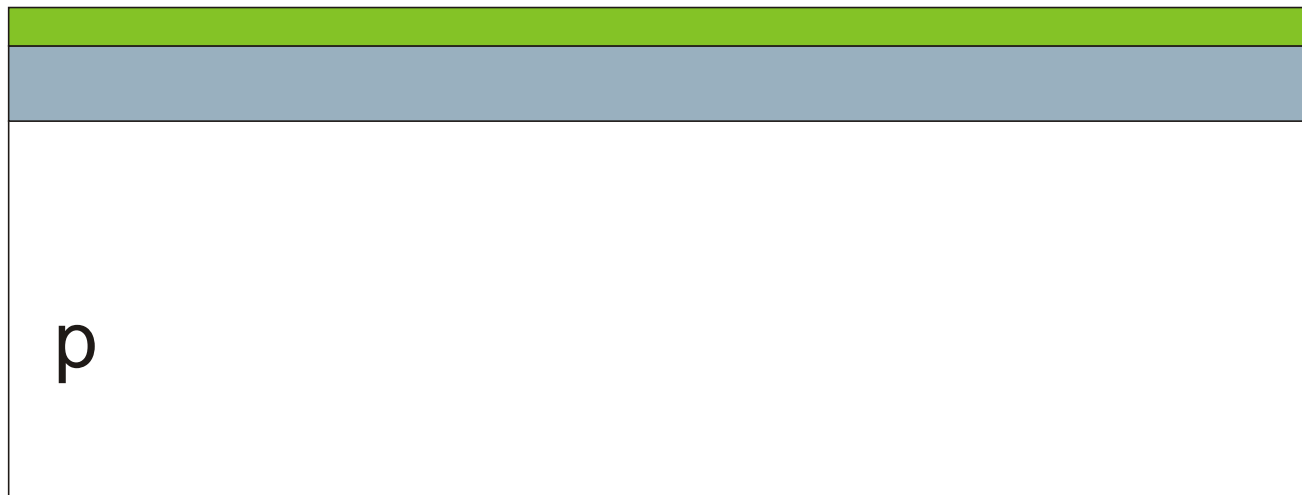


# N-well CMOS Process

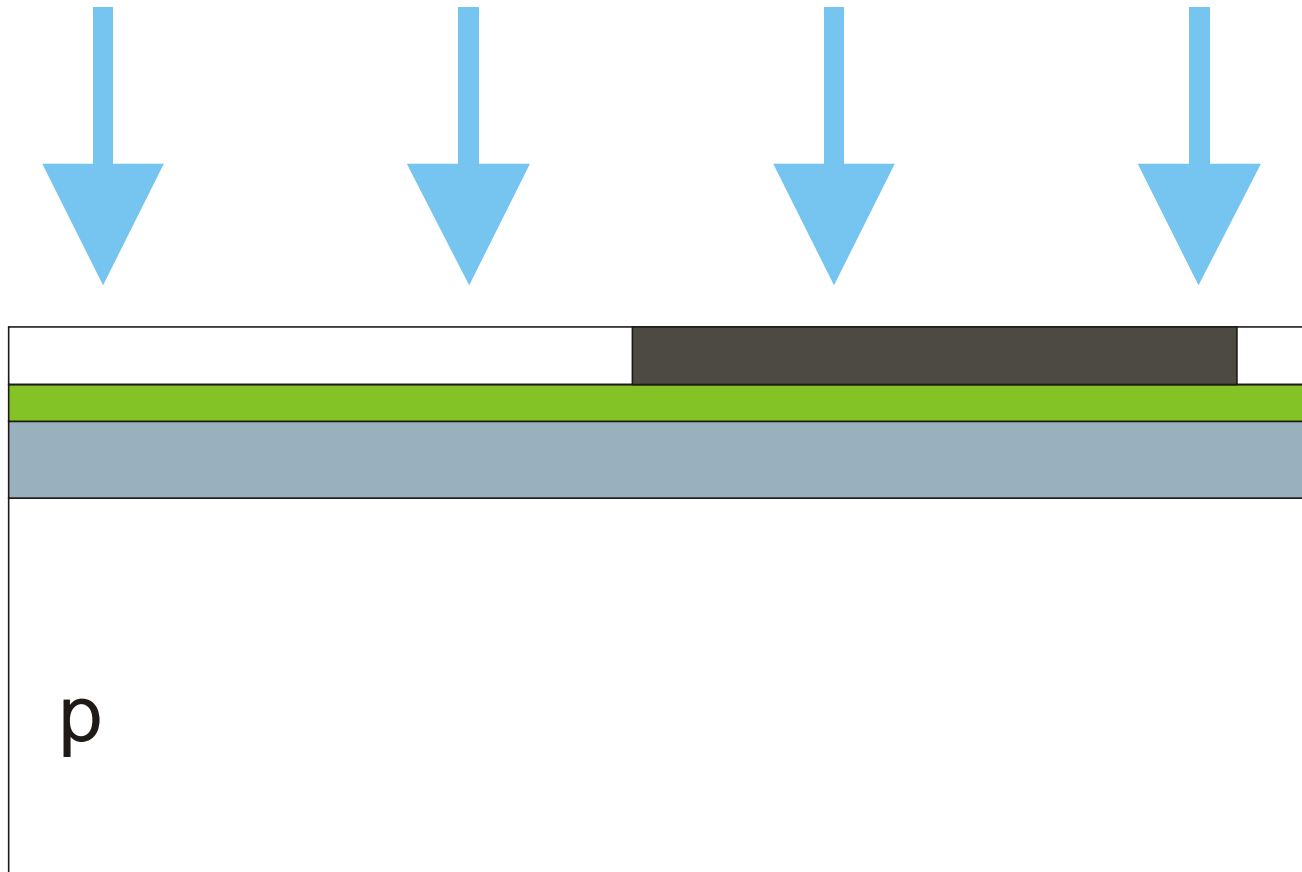
# Substrate Oxidation



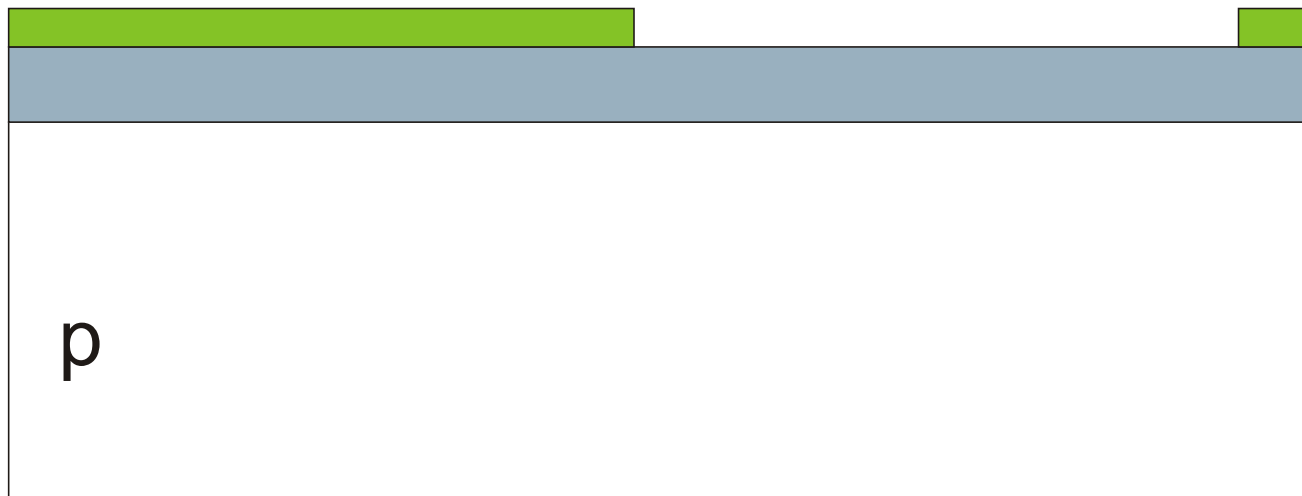
# Deposition of Photoresist



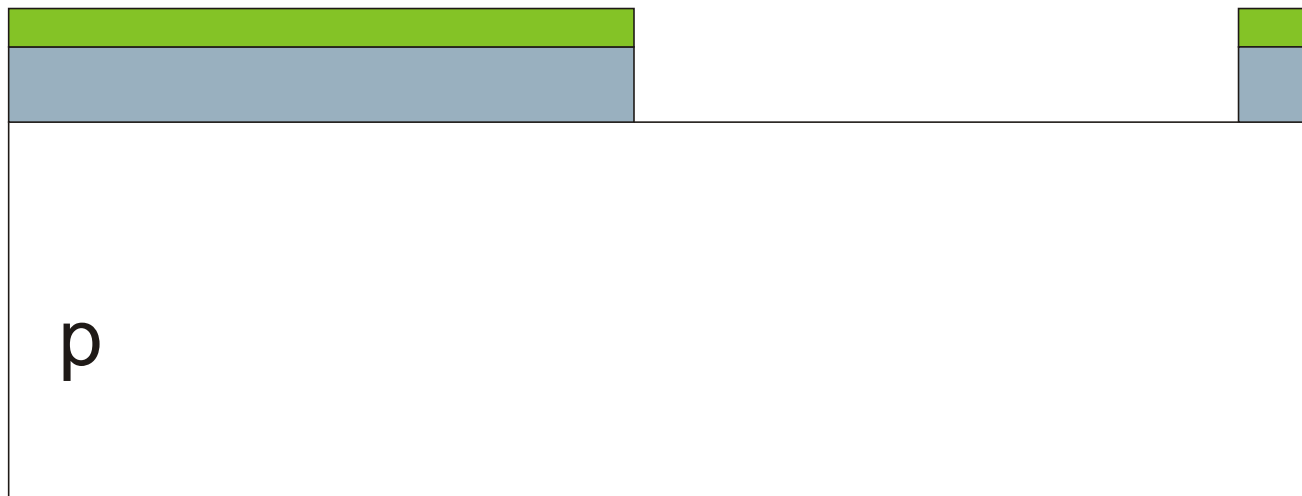
# Masking and Projection



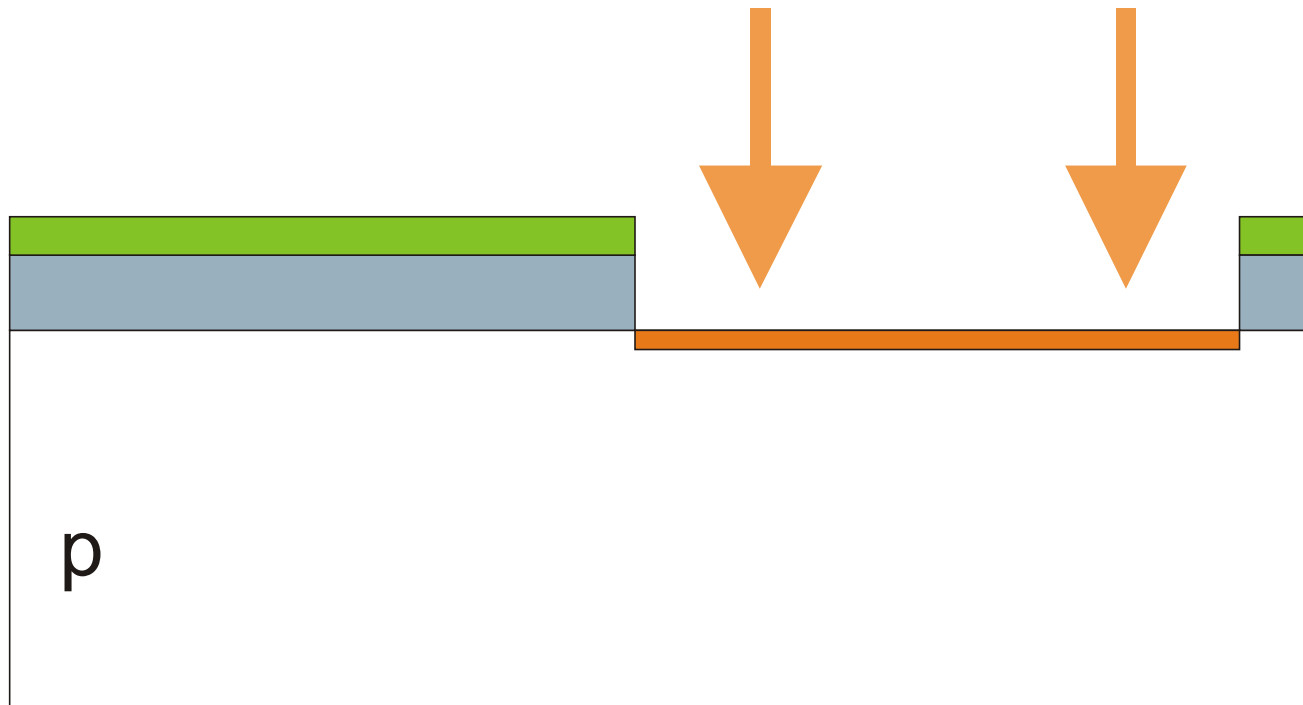
# Developing of Photoresist



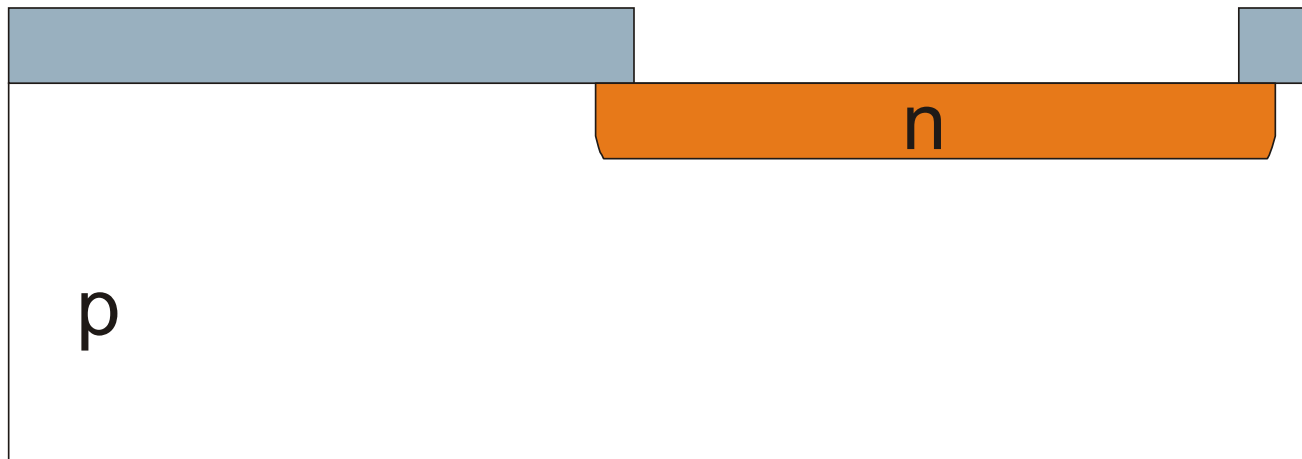
# Oxide Etch



# Ion Implantation

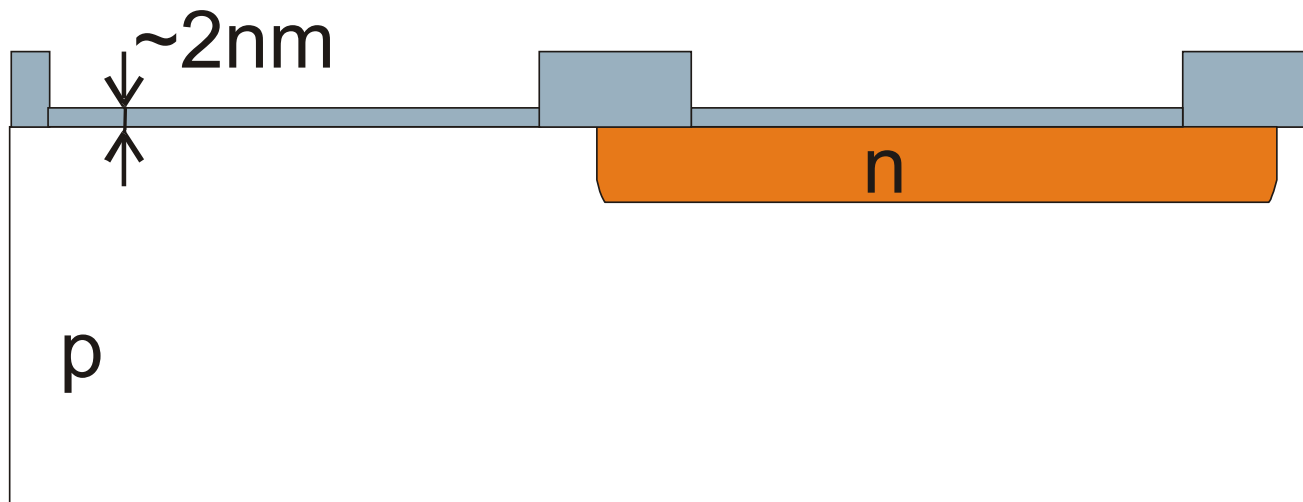


# Annealing / Rediffusion

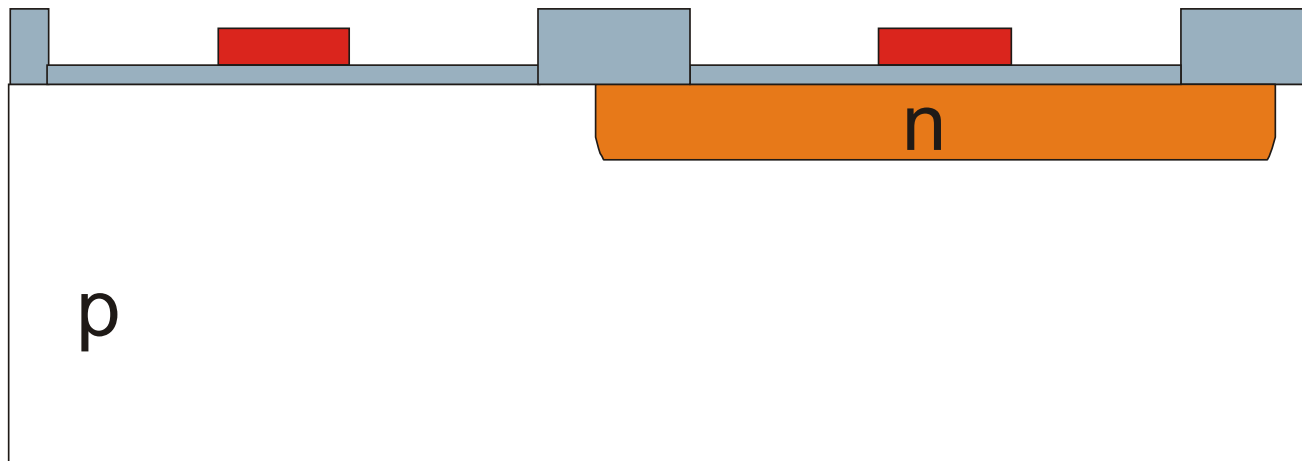




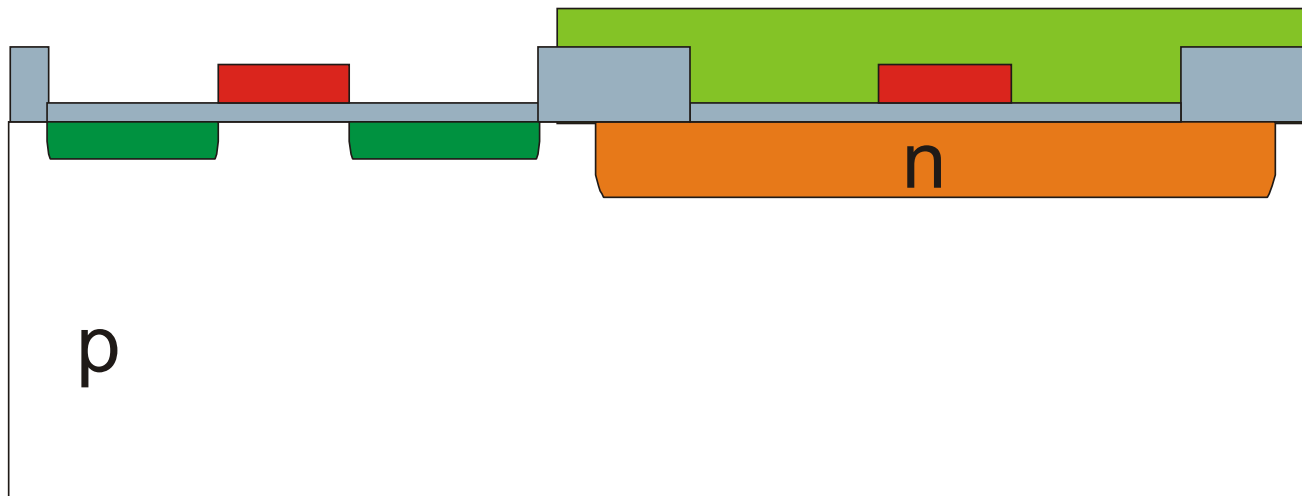
# Gate Oxide



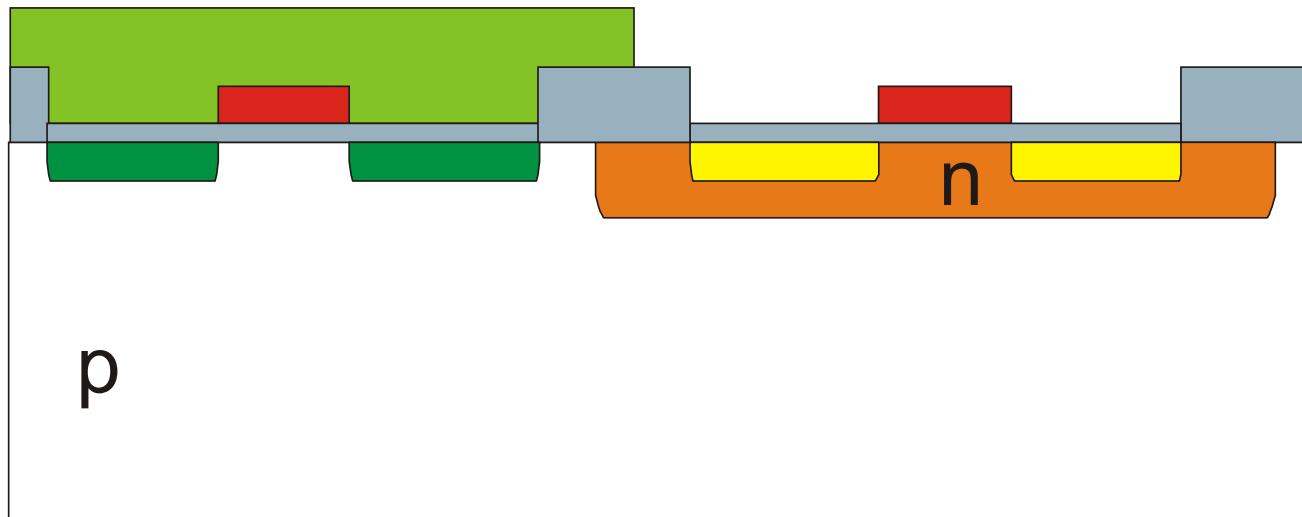
# Deposition, Masking and Etching of Polysilicon



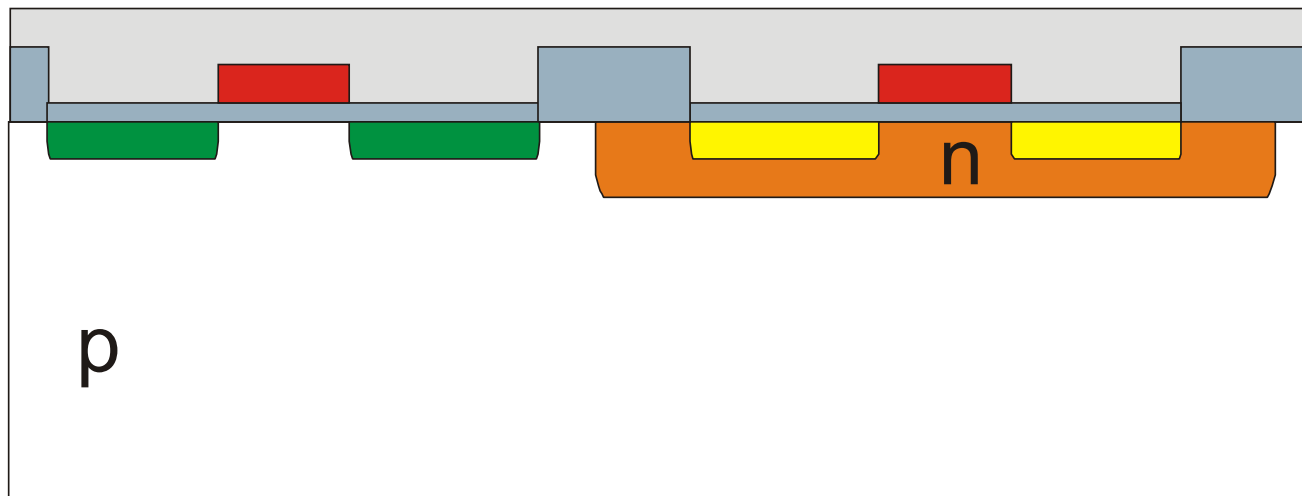
# NMOS Manufacturing



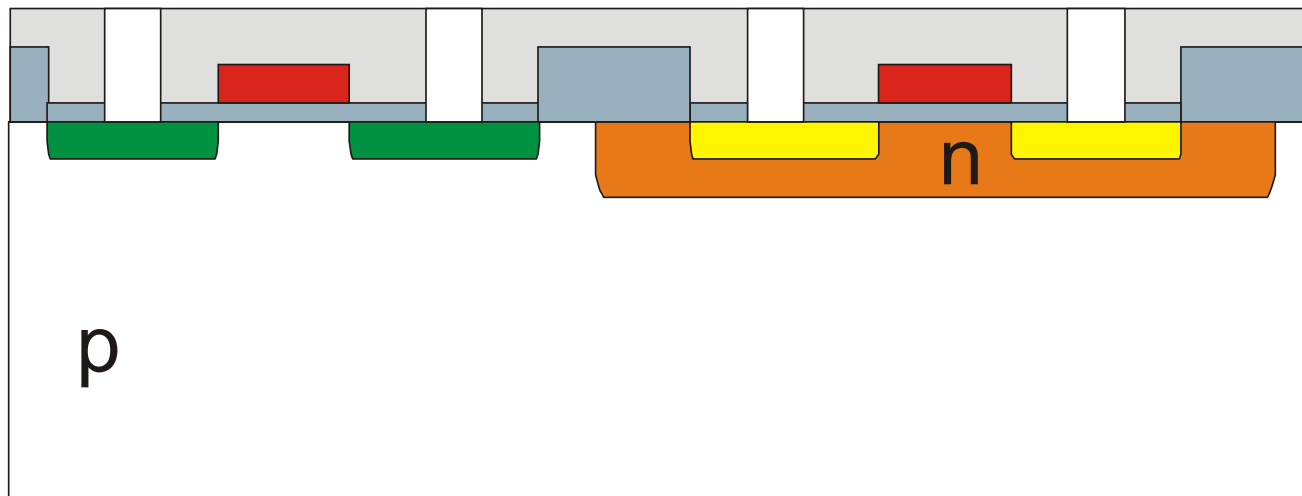
# PMOS Manufacturing



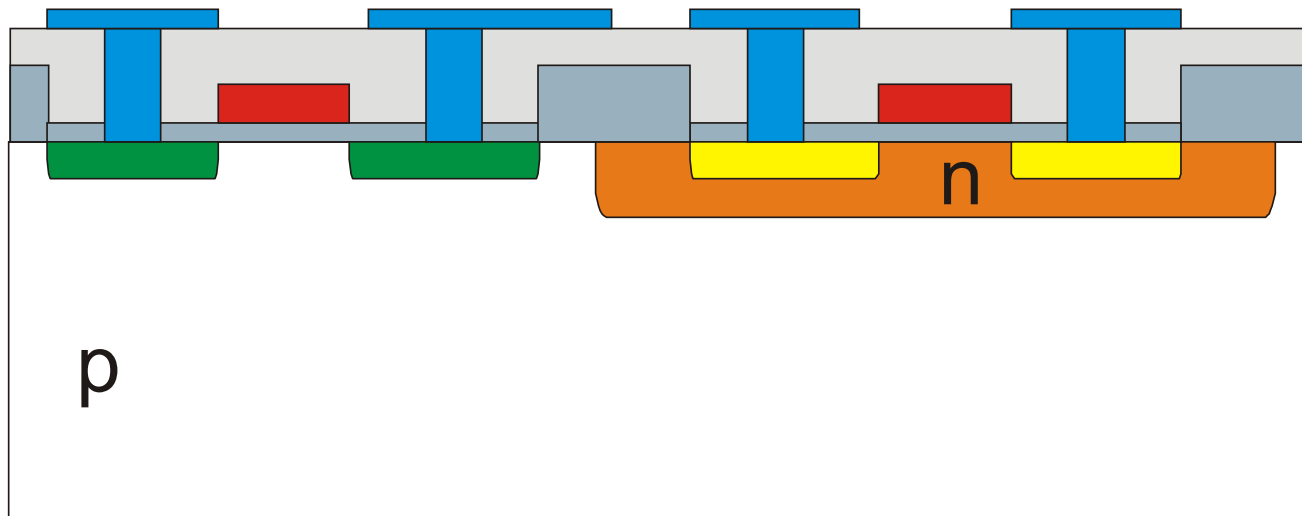
# First Insulating Layer



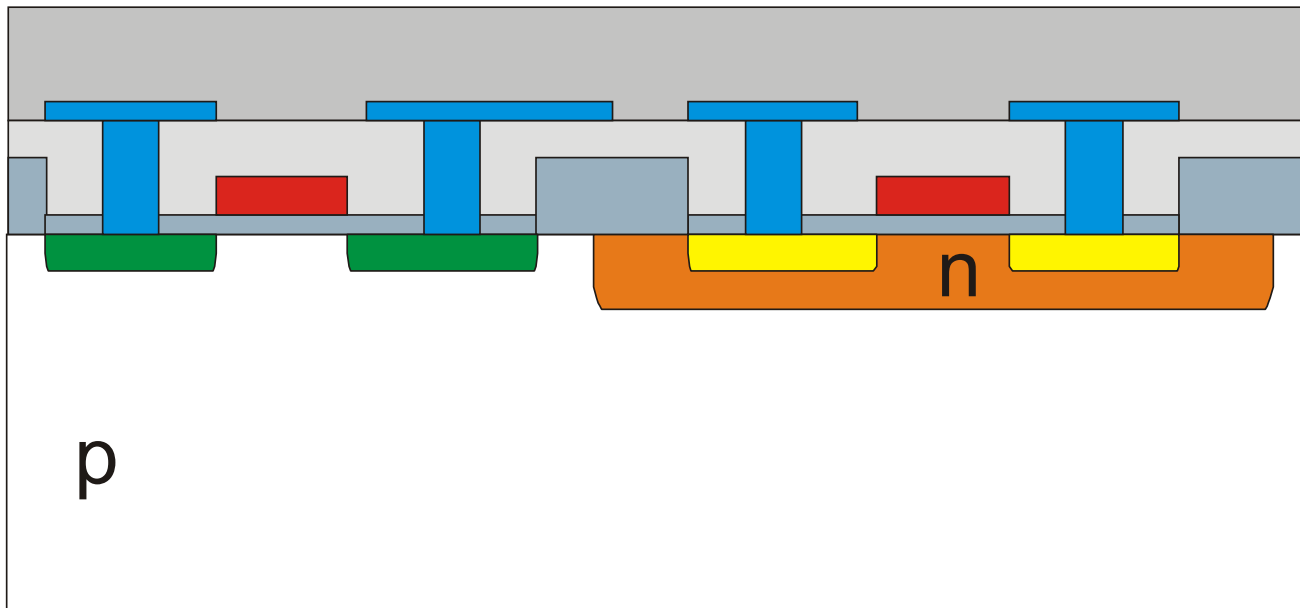
# Contact Etch



# Contacts and Metallization I

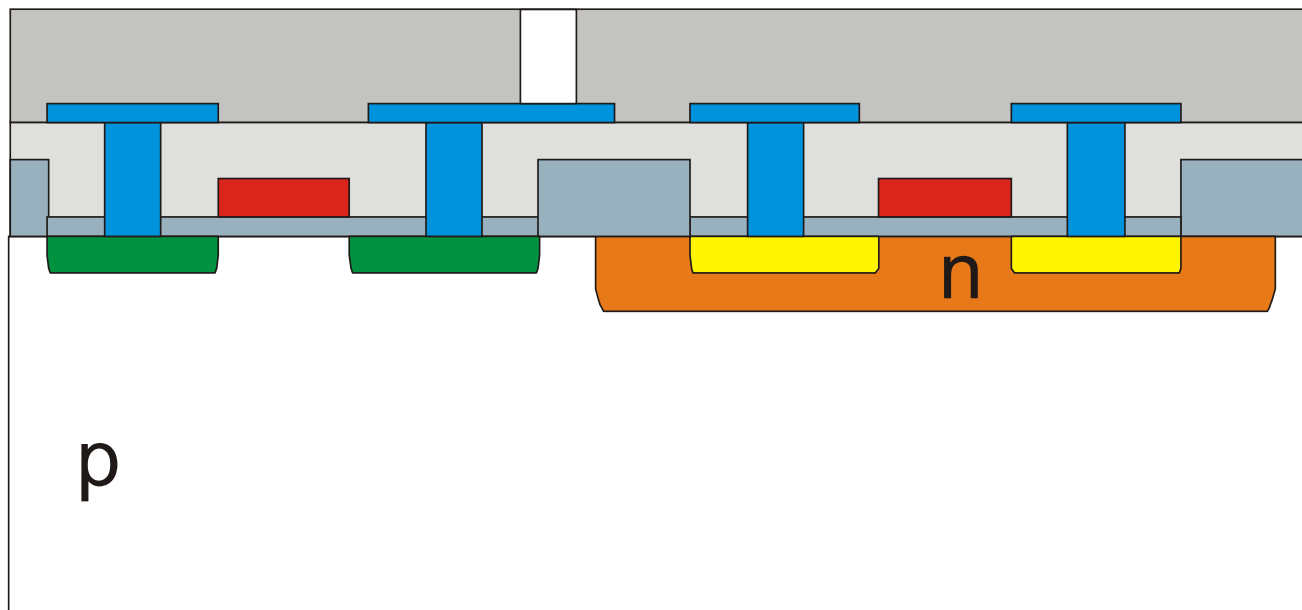


# Second Insulating Layer

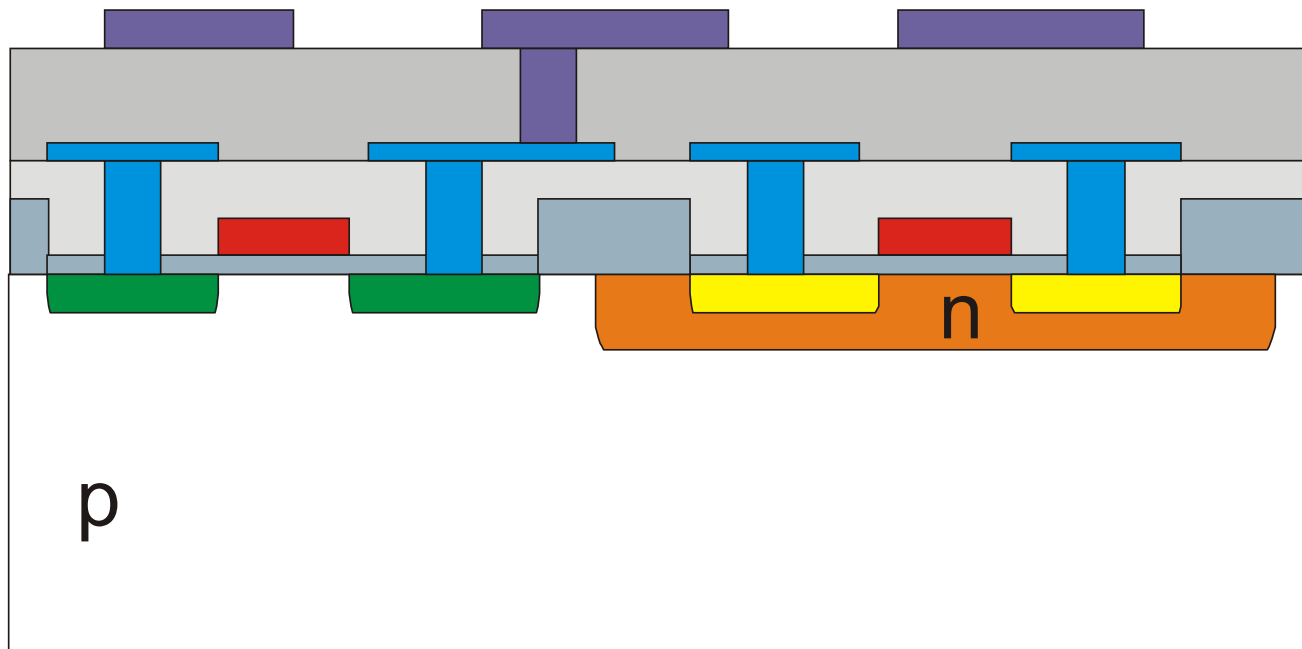




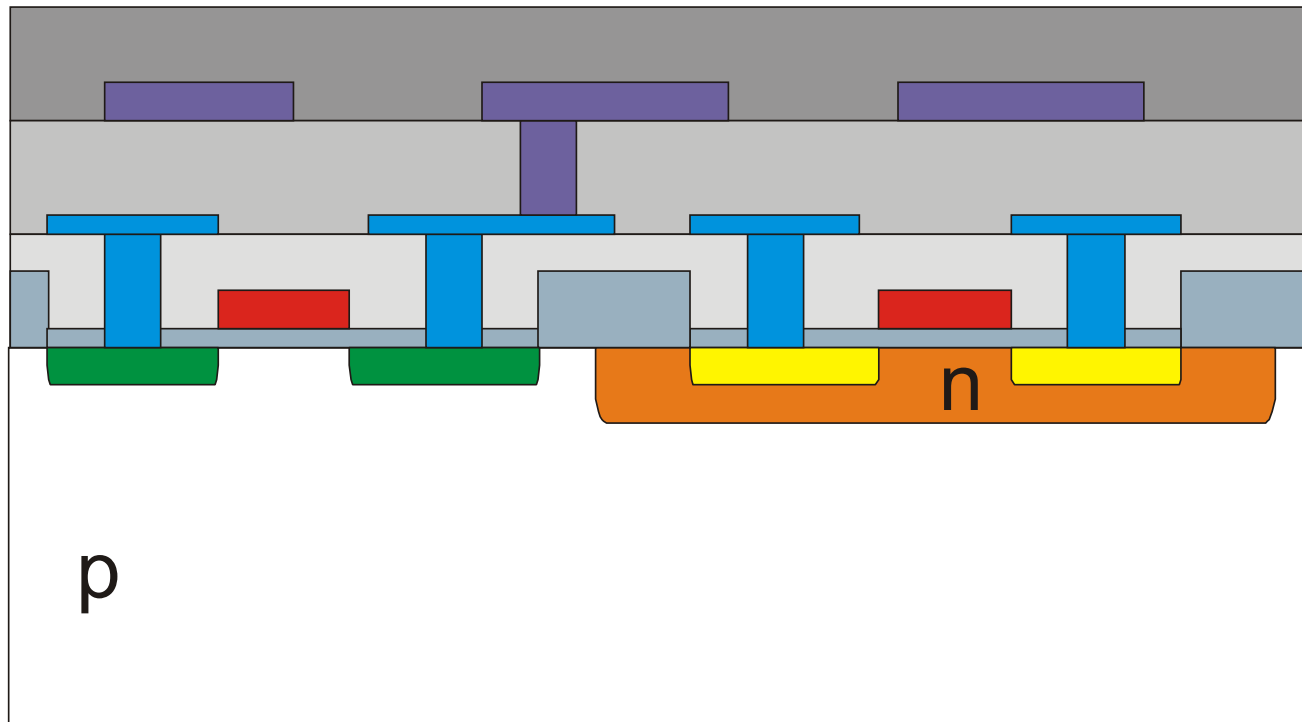
# VIA Etch



# Vias and Metallization II

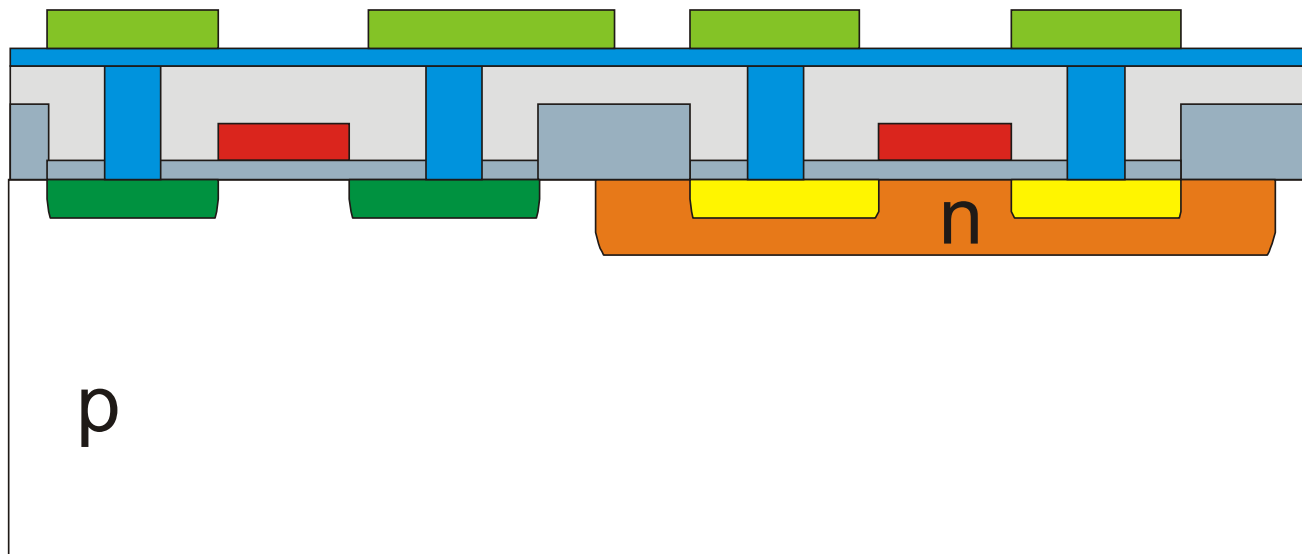


# Final Passivation

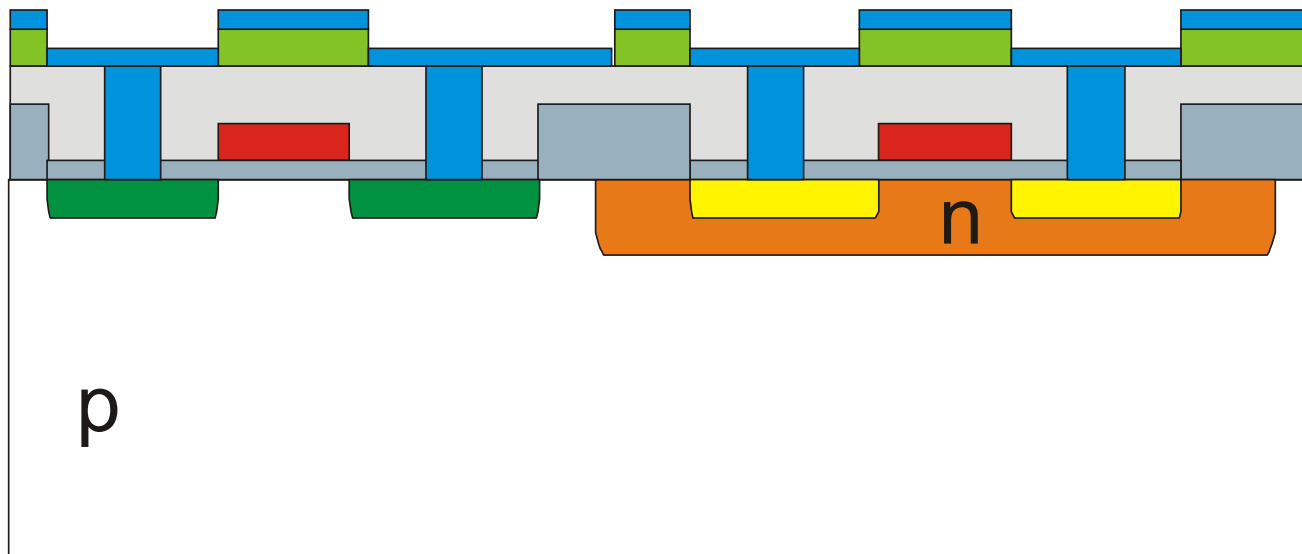


# Deposition of Metallic Layers

# Etching Away of Excessive Metal



# Lift-off



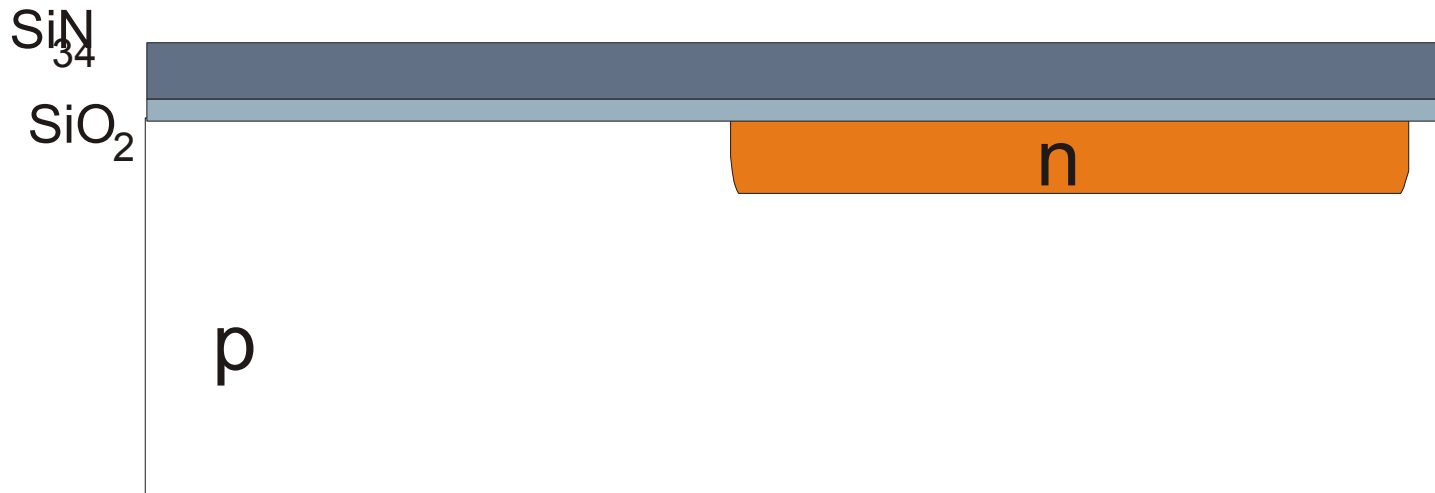
# Metal-Semiconductor Contacts

- ◆ Drain and source pins
- ◆ Substrate and well bias
- ◆ Always to heavily doped semiconductor
  - ◆ low ohmic resistance
  - ◆ no Schottky junction

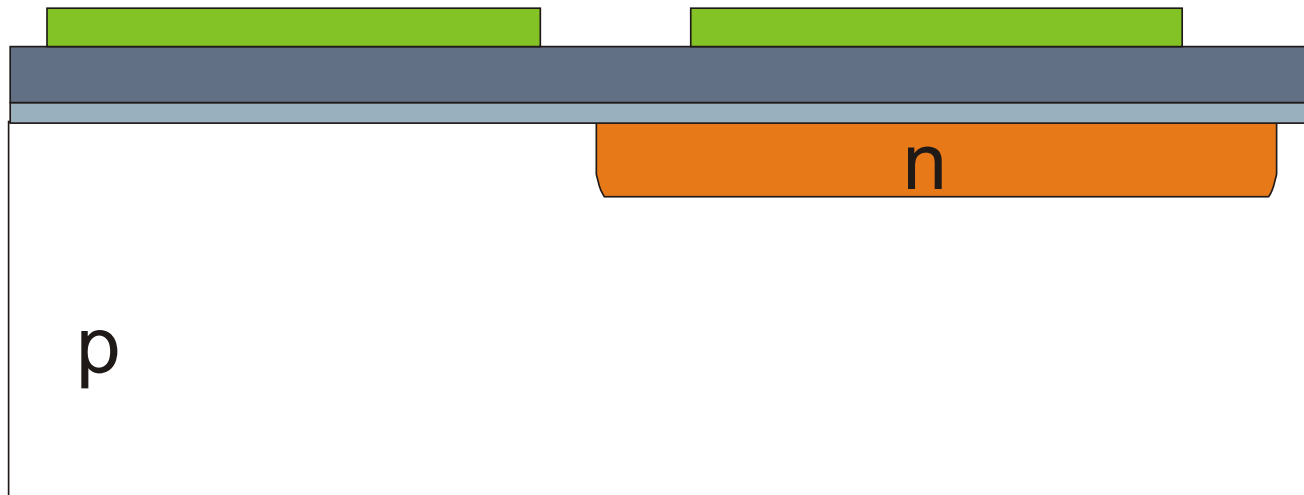
# LOCOS Technology



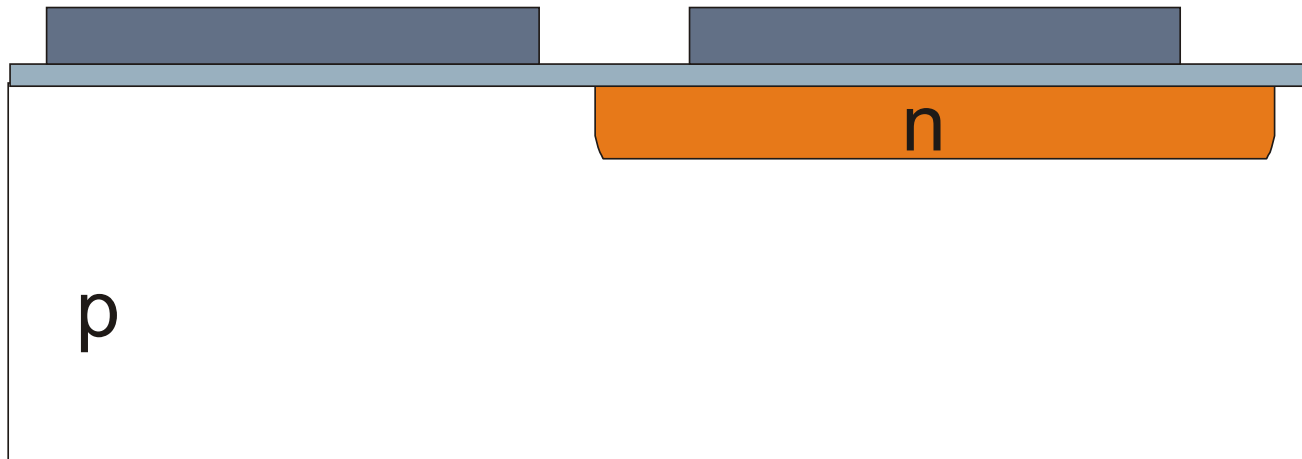
# Deposition of Silicon Dioxide and Silicon Nitride



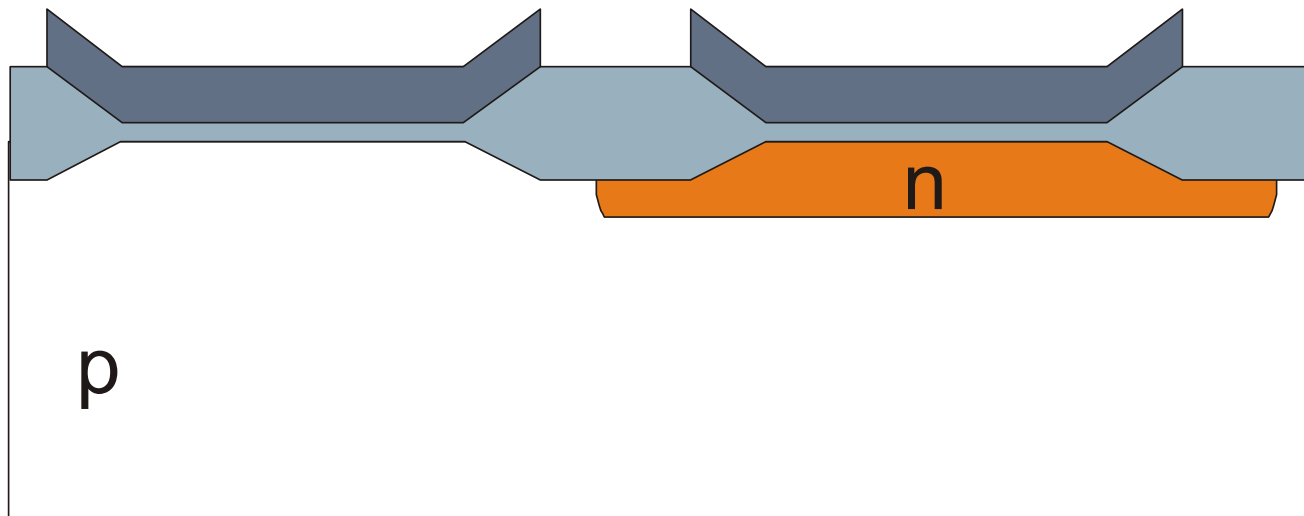
# Deposition, Masking and Etching of Photoresist



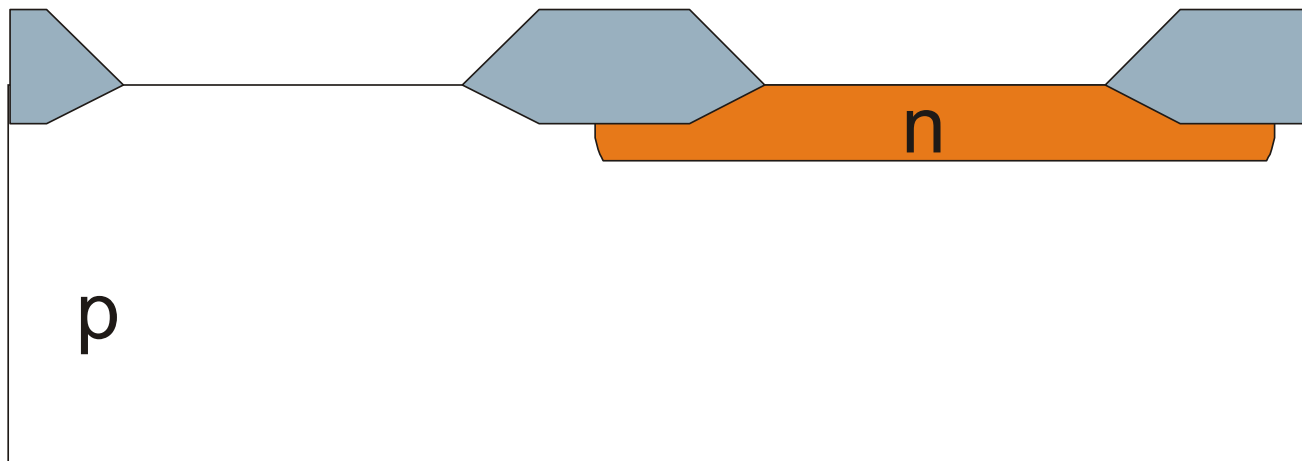
# Etching of Nitride and Removal of Photoresist



# Field Oxide Manufacturing

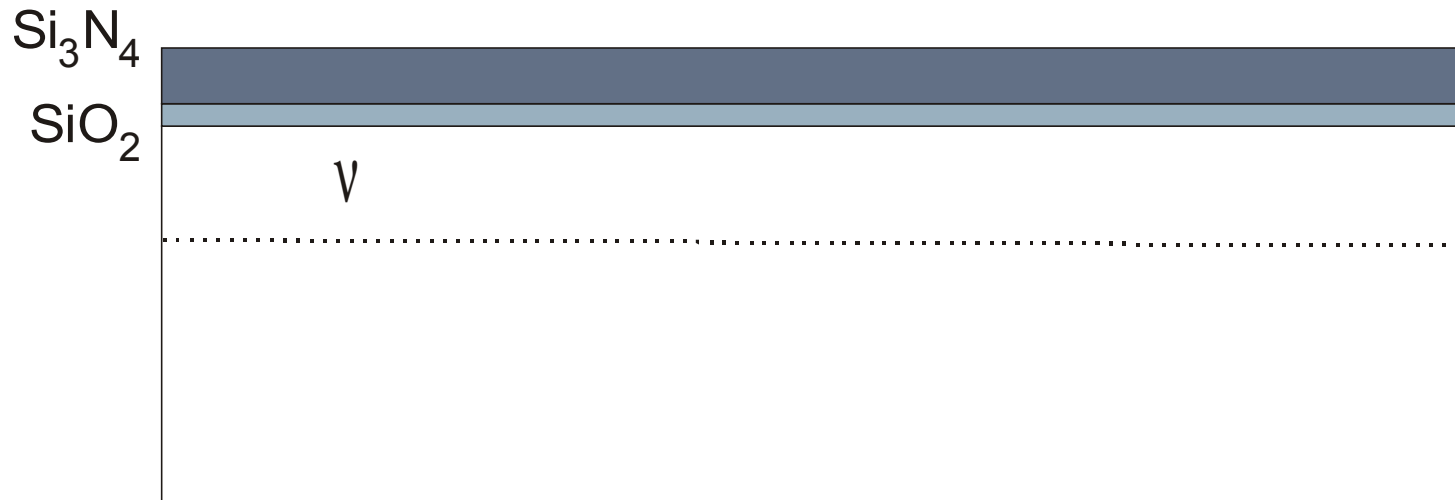


# Removal of Nitride and Thin Oxide

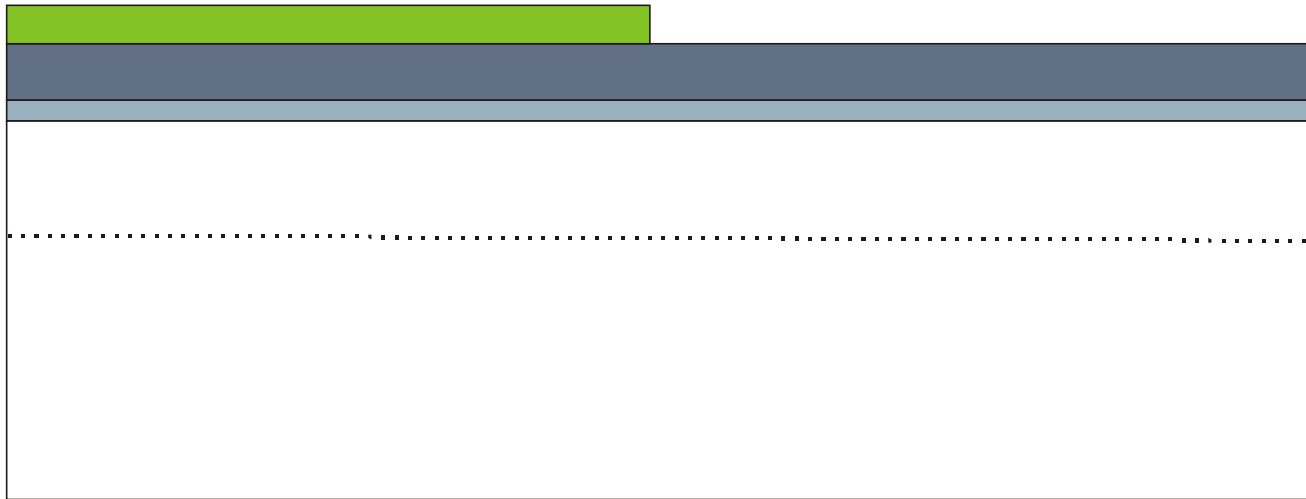


# Twin-Well (Twin-Tub) Technology

# Epitaxial Layer Covered by Oxide and Nitride

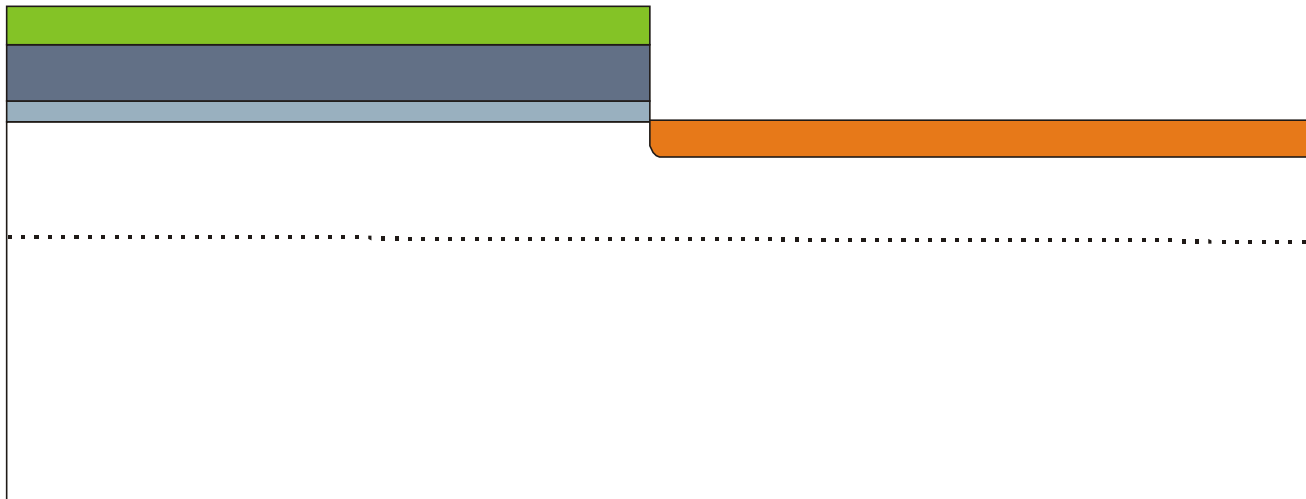


# Photoresist Deposition, Projection, Developing and Removal

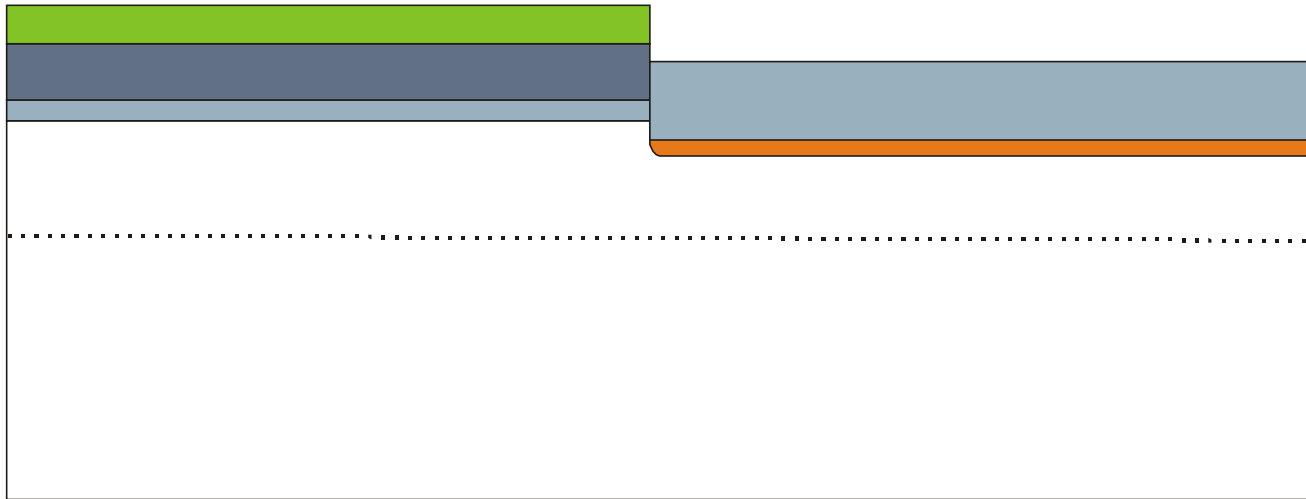




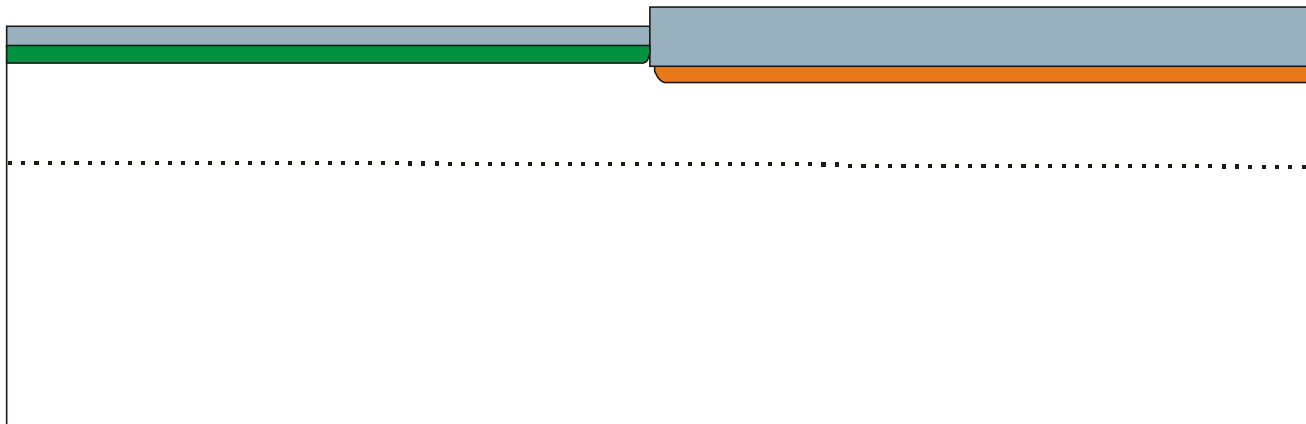
# N-Well Implantation



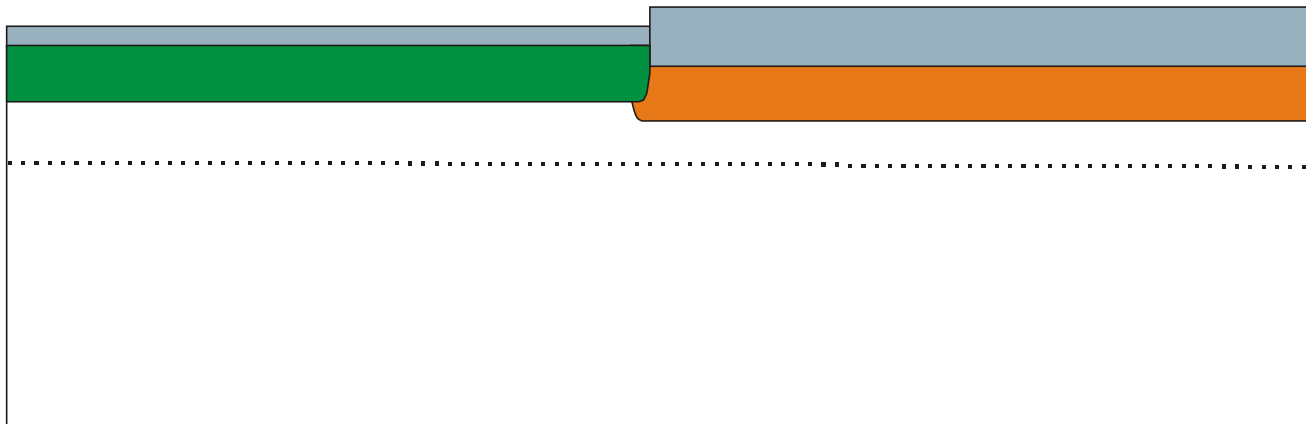
# Thick Oxide



# P-Well Implantation

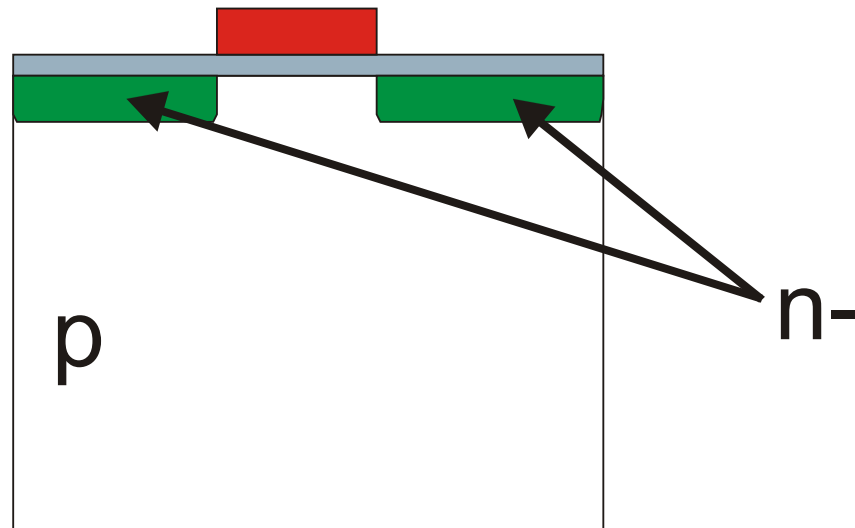


# Annealing / Rediffusion

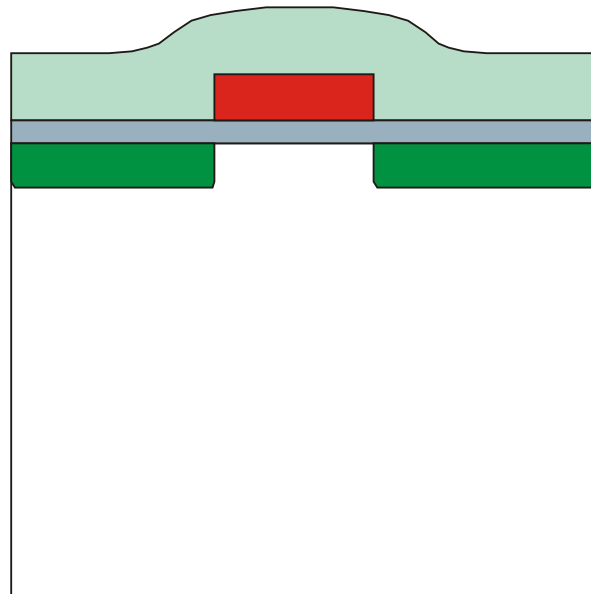


# Lightly Doped Drain (LDD) Transistor

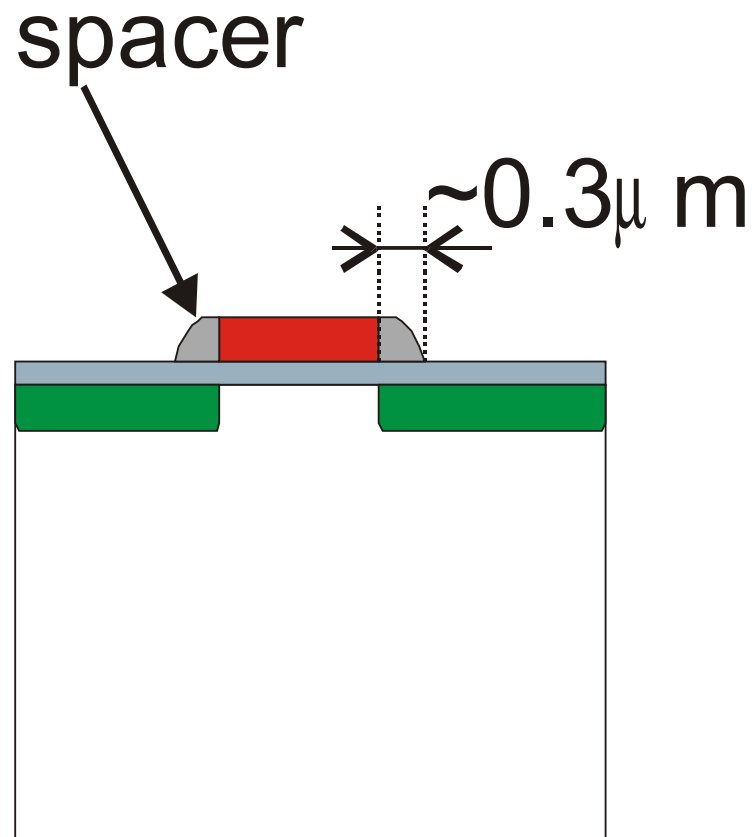
# Implantation of Lightly Doped Drain and Source Areas



# CVD of SiO<sub>2</sub>

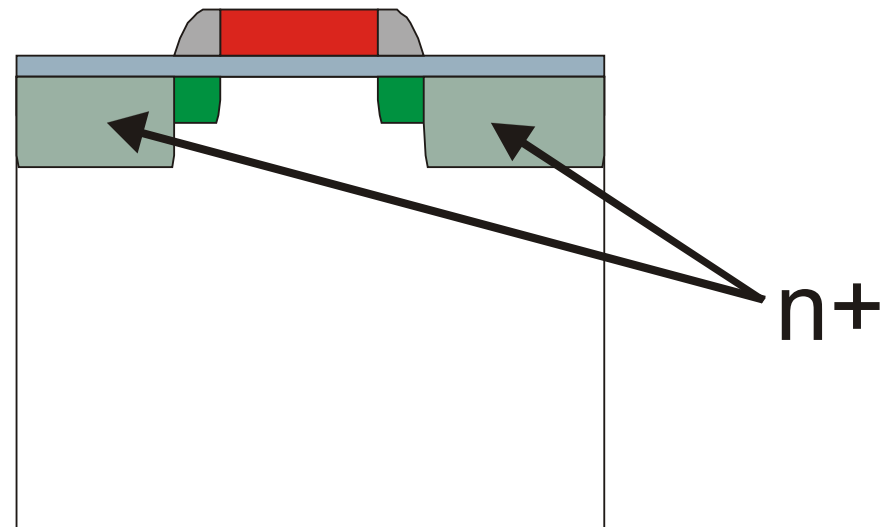


# SiO<sub>2</sub> Etch

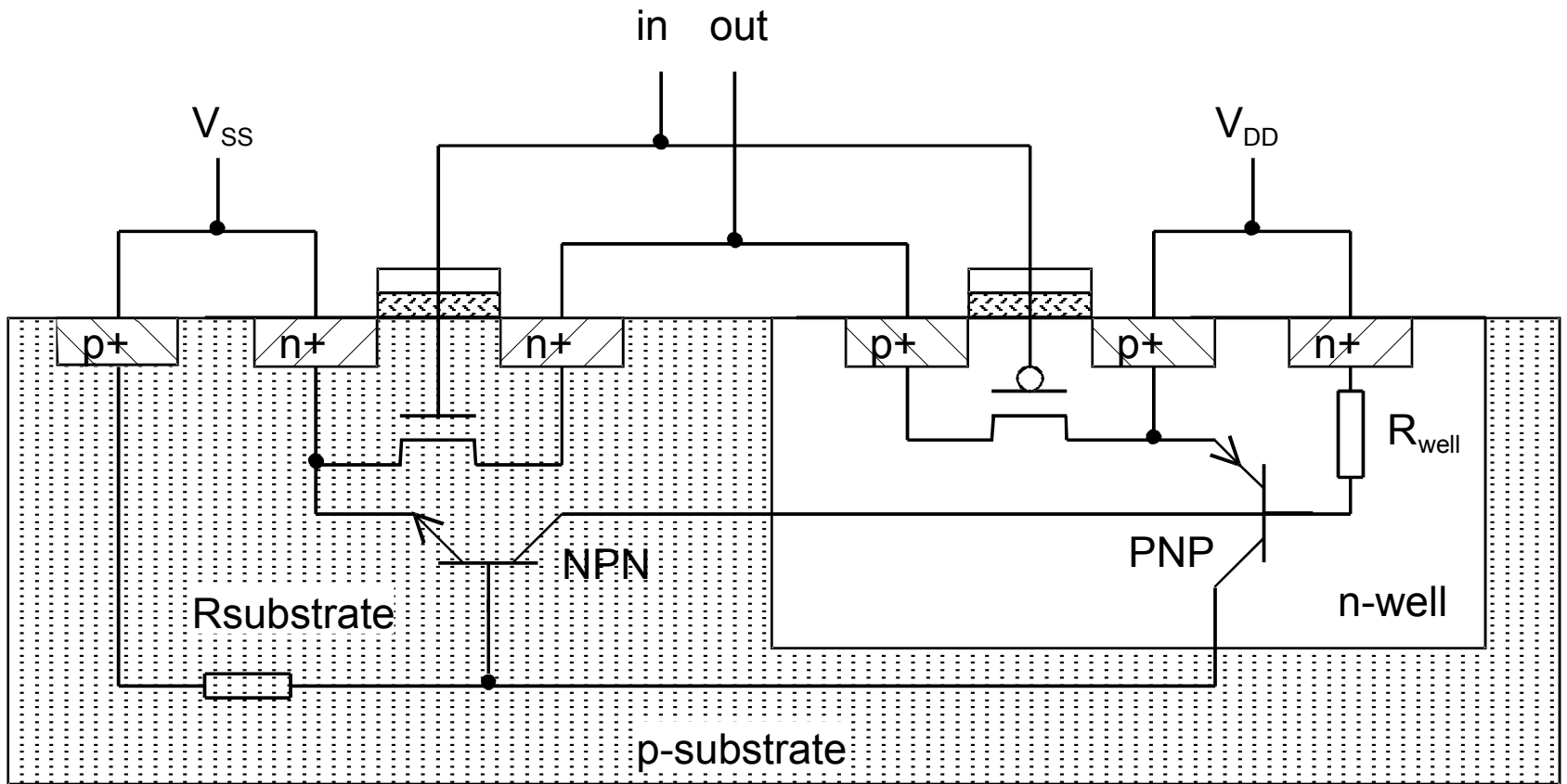




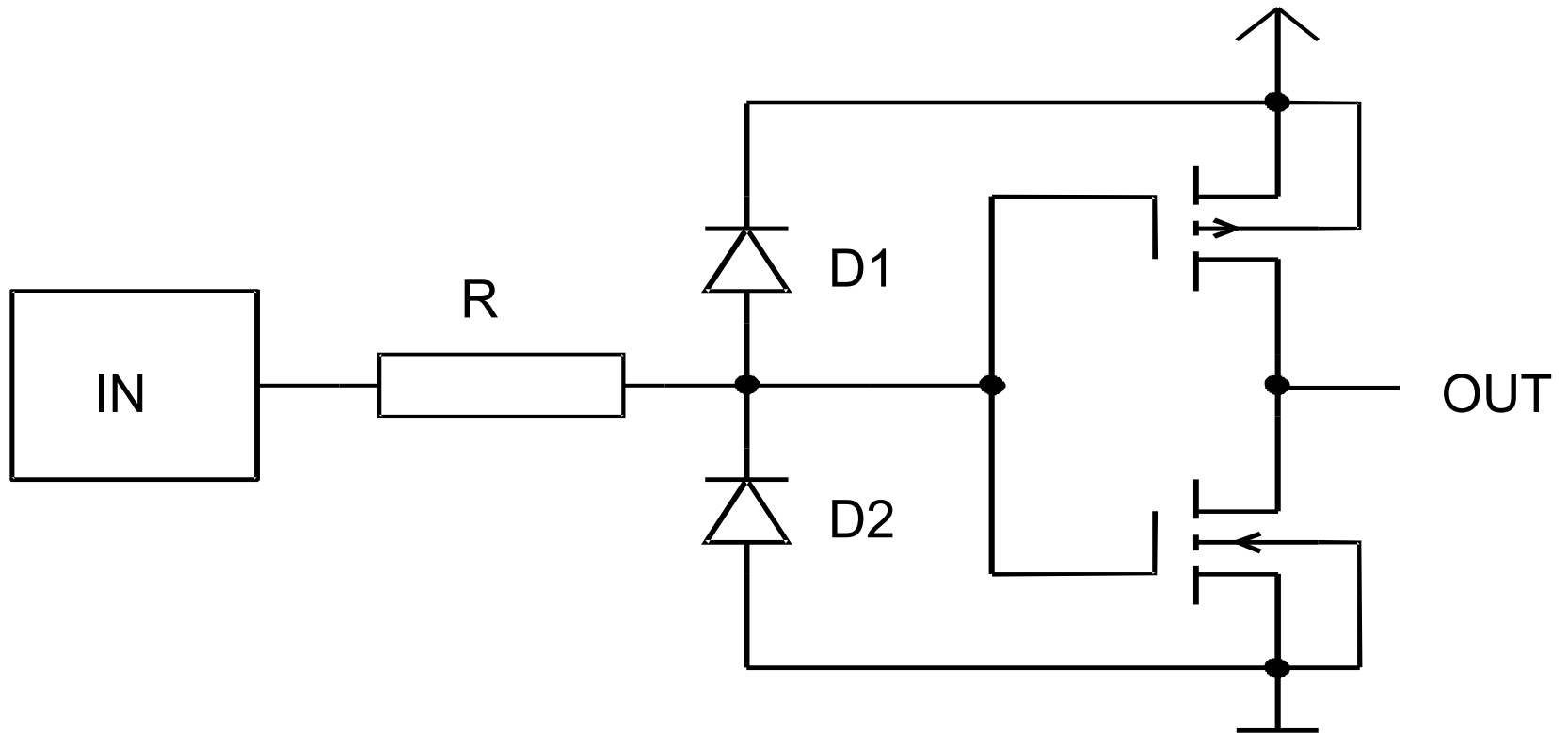
# Drain and Source Implantation



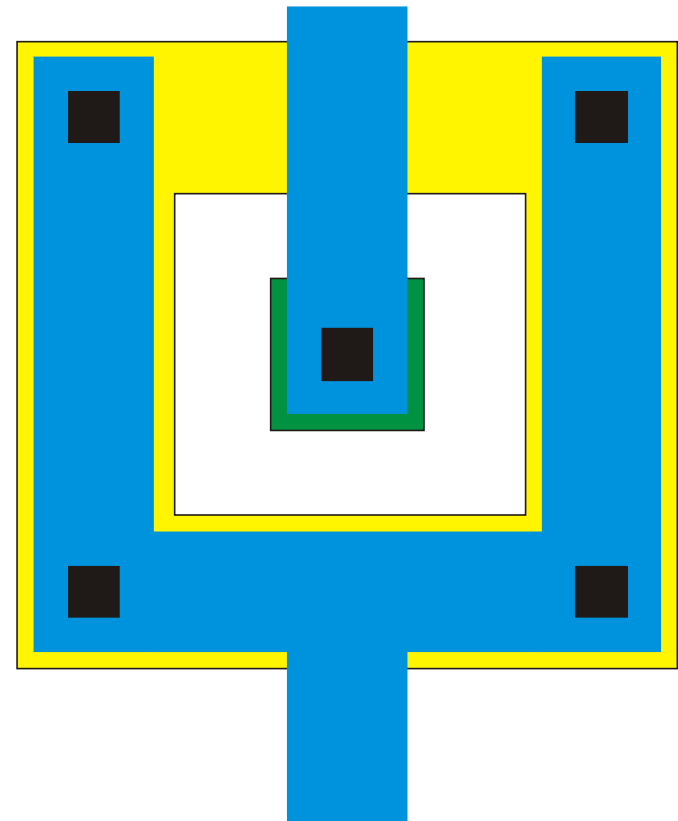
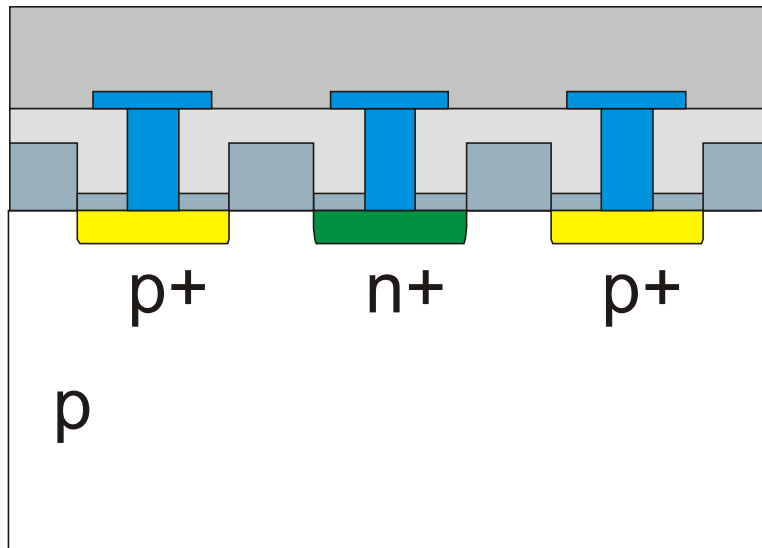
# Latch-up



# Input Protection Circuit



# n+/p Diode



# p<sup>+</sup>/n Diode

